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# **Surface Analysis of Additive Manufacturing Processes**

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## **Message from the Guest Editors**

Additive manufacturing (AM) has emerged as a versatile, enabling technology, outperforming tradition manufacturing technologies in numerous applications. This processing technology has been adapted to an increasingly varied range of materials to fabricate complex structures with novel geometries. However, the surface quality of AM parts needs to be improved. Surface analysis of AM processes is therefore an important area of research.

This Special Issue aims to compile the latest research on the surface analysis of AM processes, covering a broad range of topics and applications, including but not limiting to:

- Characterization of surface topography, structures, texture and roughness in AM parts.
- Surface modification techniques to enhance the properties of AM parts.
- Development of in situ monitoring techniques for surface quality during AM processing.
- Investigation of the impact of process parameters on surface quality.
- Surface analysis of hybrid AM processes, such as multi-material and multi-process approaches.
- Development of modeling and simulation approaches to predict and optimize surface quality in AM processes.











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# **Message from the Editor-in-Chief**

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